High Capacitance Stacked Capacitors

TEP / TEV Series

FEATURES

- Multilayer chips ceramic capacitors
- NP0 dielectric
- Capacitance range: 10nF to 2.7µF
- Voltage range: 63 V_{DC} to 500 V_{DC}

PHYSICAL CHARACTERISTICS

CONSTRUCTION

Radial leaded varnished stacked chips capacitors for through-hole circuits

MARKING (clear or coded)

Series, Capacitance value, tolerance, rated voltage, date code.

ELECTRICAL SPECIFICATIONS

DIELECTRIC	NP0
Maximum ΔC/°C over temperature range without voltage	NA
Temperature coefficient	(0±30)ppm/°C
Ageing	None
Operating temperature	−55°C to +125°C
Rated voltage (U_{RC})	63 V_{DC} to 500 V_{DC}
Dielectric withstanding voltage	2.5 U_{RC} for U_{RC} < 500 V_{DC} 2 U_{RC} for U_{RC} = 500 V_{DC}
Capacitance	at 1kHz
Dissipation factor	≤ 0.15% at 1kHz
Insulation resistance at 25°C under U_{RC}	≥ 1,000 MΩ.µF

HIGH CAPACITANCE

HOW TO ORDER

TEP	53	W	F	120nF	±10%	200 V
Series	Exxelia size code	RoHS compliant	Quality level	Capacitance	Tolerance	Rated voltage
TEP = radial leads vertical stack **TEV** = radial leads horizontal stack	**53** **54** **55** **56** **57** **58** **65**	**-** = No RoHS **W** = RoHS compliant	**-** = standard quality level **F** = Hi-Rel quality: screening in accordance with Exxelia specification	Capacitance value in clear	**±1%** **±2%** **±5%** **±10%** **±20%**	**63V** **100V** **200V** **500V**

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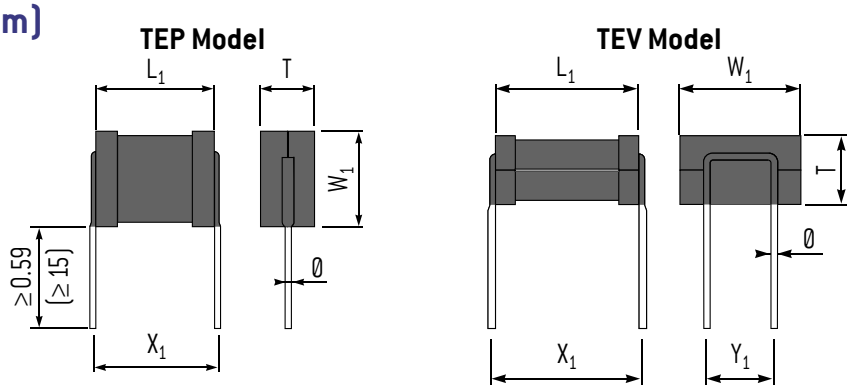
DIMENSIONS in inches (mm)



STANDARD RATINGS

	Size	3033	3740	5550	6080	40140	80150	8060
	Exxelia size code	53	54	55	56	57	58	65
Dimensions inches (mm)	L_1 max.	0.418 (10.6)	0.493 (12.5)	0.623 (15.8)	0.701 (17.8)	0.556 (14.1)	0.894 (22.7)	0.894 (22.7)
	W_1 max.	0.363 (9.2)	0.473 (12)	0.536 (13.6)	0.851 (21.6)	1.504 (38.2)	1.599 (40.6)	0.654 (16.6)
	X_1 max.	0.323 ± 0.02 (8.2 ± 0.5)	0.4 ± 0.02 (10.16 ± 0.5)	0.579 ± 0.02 (14.7 ± 0.5)	0.6 ± 0.02 (15.24 ± 0.5)	0.4 ± 0.02 (10.16 ± 0.5)	0.835 ± 0.02 (21.2 ± 0.5)	0.835 ± 0.02 (21.2 ± 0.5)
	Y_1 max.	0.2 ± 0.02 (5.08 ± 0.5)	0.3 ± 0.02 (7.62 ± 0.5)	0.3 ± 0.02 (7.62 ± 0.5)	0.6 ± 0.02 (15.24 ± 0.5)	1.1 ± 0.02 (27.94 ± 0.5)	1.2 ± 0.02 (30.48 ± 0.5)	0.4 ± 0.02 (10.16 ± 0.5)
	Leads diameter Ø	See table below						

Min. Capacitance value		10nF	18nF	33nF	68nF	100nF	150nF	68nF	T max. inches (mm)		Nb. of chips
Rated voltage (U_{RC})	63 V	100nF	180nF	330nF	680nF	820nF	1.8µF	680nF	0.158	(4)	1
		220nF	330nF	560nF	1.2µF	1.5µF	3.3µF	1.2µF	0.315	(8)	2
		330nF	470nF	820nF	1.8µF	2.2µF	4.7µF	1.8µF	0.473	(12)	3
		470nF	680nF	1.2µF	2.7µF	3.3µF	6.8µF	2.7µF	0.630	(16)	4
	100 V	82nF	120nF	220nF	470nF	560nF	1.2µF	470nF	0.158	(4)	1
		180nF	270nF	470nF	1µF	1.2µF	2.7µF	1µF	0.315	(8)	2
		270nF	390nF	680nF	1.5µF	1.8µF	3.9µF	1.5µF	0.473	(12)	3
		330nF	470nF	1µF	1.8µF	2.2µF	4.7µF	1.8µF	0.630	(16)	4
	200 V	56nF	82nF	180nF	330nF	390nF	820nF	330nF	0.158	(4)	1
		120nF	180nF	330nF	680nF	820nF	1.5µF	680nF	0.315	(8)	2
		180nF	270nF	470nF	1µF	1.2µF	2.7µF	1µF	0.473	(12)	3
		220nF	330nF	680nF	1.2µF	1.5µF	3.3µF	1.2µF	0.630	(16)	4
	500 V	18nF	27nF	56nF	100nF	150nF	270nF	100nF	0.158	(4)	1
		33nF	56nF	120nF	220nF	270nF	560nF	220nF	0.315	(8)	2
		56nF	100nF	180nF	330nF	390nF	820nF	330nF	0.473	(12)	3
		68nF	120nF	220nF	390nF	470nF	1.2µF	390nF	0.630	(16)	4

Available capacitance values:
NP0 dielectric: E6, E12, E24 (see page 14). Specific values upon request.
The above table defines the standard products, other components may be built upon request.

	TEP 53 - TEP 54 - TEP 55	TEP 56 - TEP 65	TEV 53	TEV 54 - TEV 55 - TEV 56 - TEV 65
T max.	Leads diameter Ø (±10%) inches (mm)			
4	0.024 (0.6)	0.031 (0.8)	0.031 (0.8)	0.039 (1)
8	0.024 (0.6)	0.031 (0.8)	0.031 (0.8)	0.039 (1)
12	0.031 (0.8)	0.039 (1)	0.031 (0.8)	0.039 (1)
16	0.031 (0.8)	0.039 (1)	0.031 (0.8)	0.039 (1)

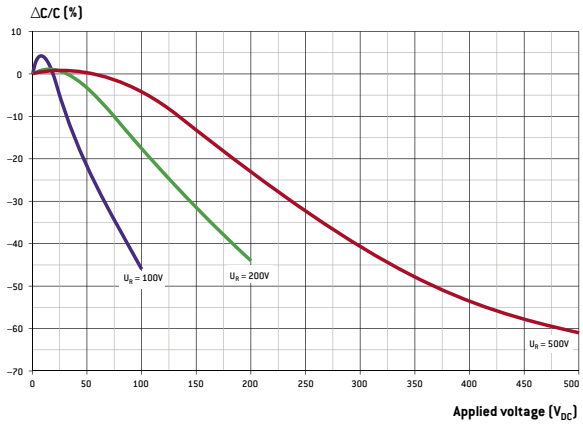
General Information

These capacitors have been developed in response to demand from switched mode power supply (S.M.P.S.) and DC-DC converters manufacturers. They are particularly suitable for filtering, smoothing and decoupling purpose in Hi-Rel equipments. The capacitors utilize advanced ceramic technology to achieve Hi-Rel long operating life and small size. They are designed for hybrid assemblies and low profile printed circuit applications.

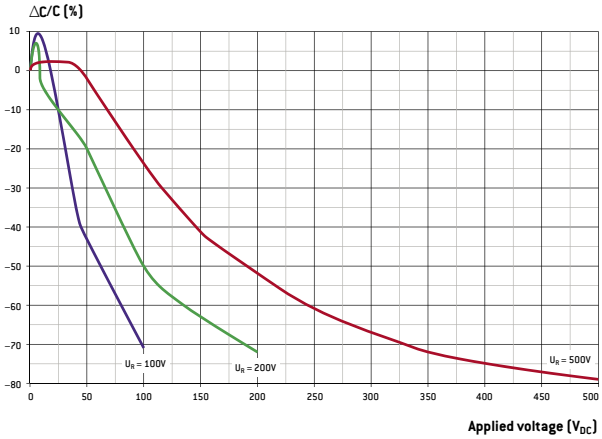
Customized assemblies may be achieved with standard bare chip sizes mentioned in the following chapters.

TYPICAL CURVES: R Series, SC/SV Series

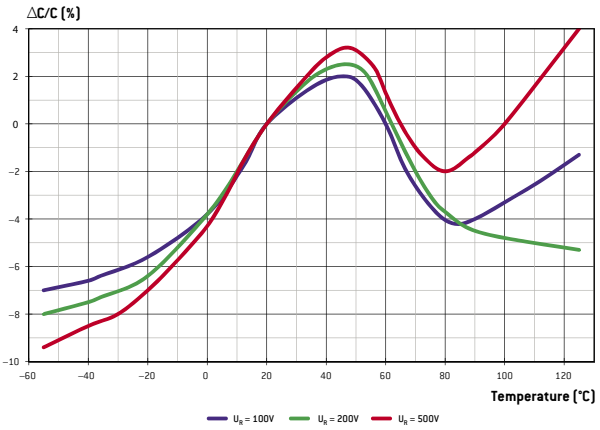
X DIELECTRIC: TYPICAL VOLTAGE COEFFICIENT AT 25°C (FOR ALL SIZES)



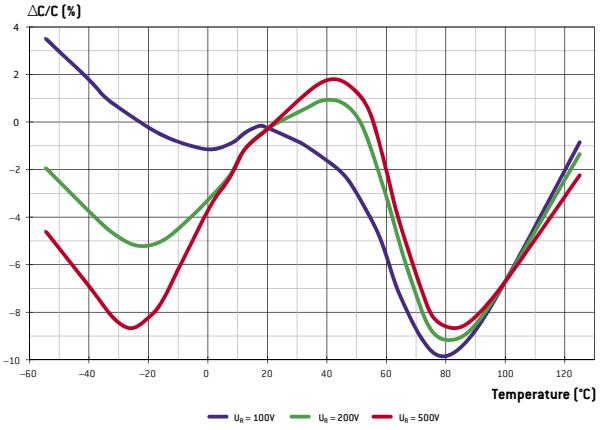
T DIELECTRIC: TYPICAL VOLTAGE COEFFICIENT AT 25°C (for all sizes)



X DIELECTRIC: TYPICAL TEMPERATURE COEFFICIENT WITHOUT VOLTAGE (for all sizes)

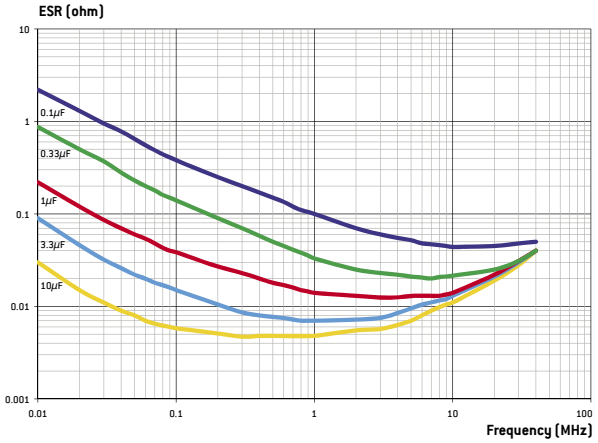


T DIELECTRIC: TYPICAL TEMPERATURE COEFFICIENT WITHOUT VOLTAGE (for all sizes)



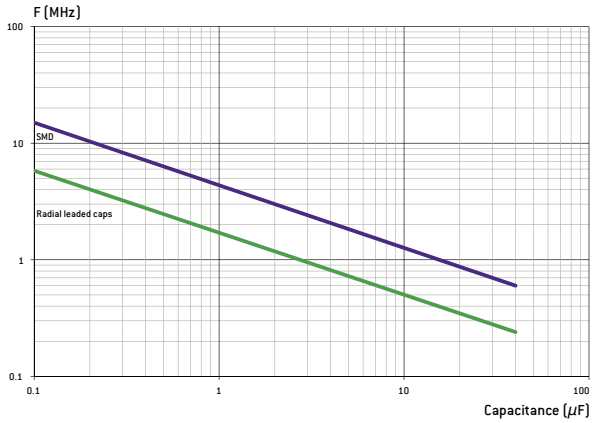
TYPICAL CURVES: R Series, SC/SV Series

TYPICAL ESR VS FREQUENCY

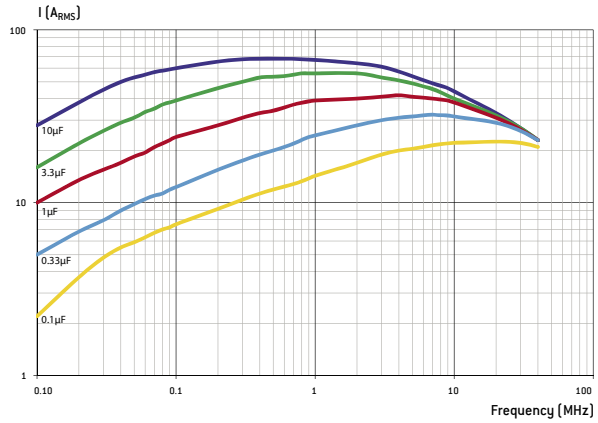


The ESR (Equivalent Serial Resistance) curves are given here for SMD (chips all case sizes) capacitors. Regarding the curves for the leaded capacitors, they are rather the same. ndeed, due to the resistivity of the raw material used and the wire diameters, the resistance of the wires is much lower than the ESR of the chips. So, in a first approach, their influence can be considered as negligible.

TYPICAL ESR VS FREQUENCY



TYPICAL MAXIMUM ADMISSIBLE CURRENT VS FREQUENCY

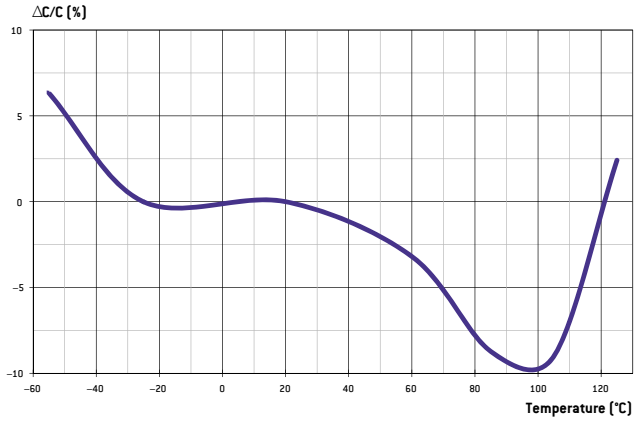


These typical curves are an example of admissible currents for one family of chip capacitors: 501R3740X chip series. For other curves and products or for further information, please contact us. Note: for the calculations, we have considered that the terminations are directly connected to an infinite heat sink. In other words, the thermal resistance of the circuit itself which depends of its type and design has not been taken into account. Moreover, the ambient temperature taken is 25°C.

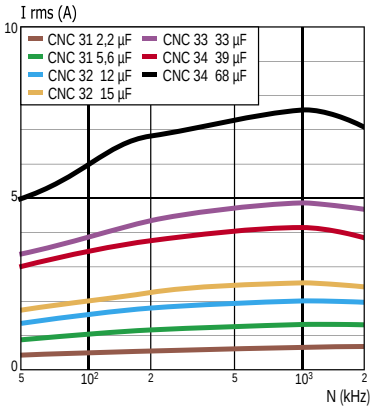
General Information

TYPICAL CURVES: CNC3X Series

TYPICAL TEMPERATURE COEFFICIENT

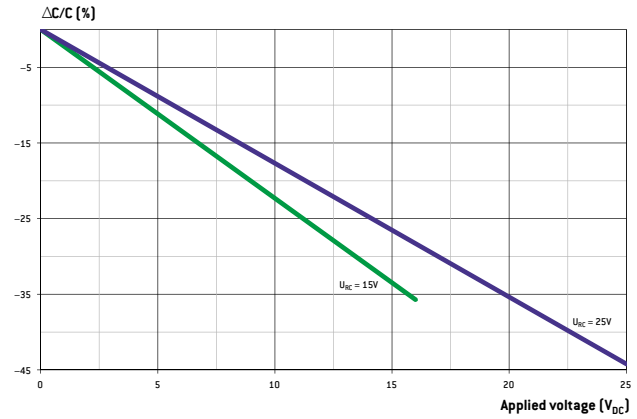


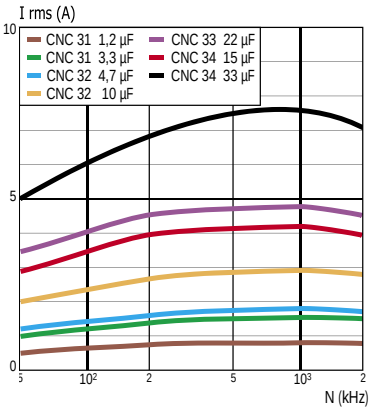
MAXIMUM CURRENT VS FREQUENCY



U_{RC} = 16V $_{DC}$ (Typical curves for Δθ = 20°C).

TYPICAL VOLTAGE COEFFICIENT

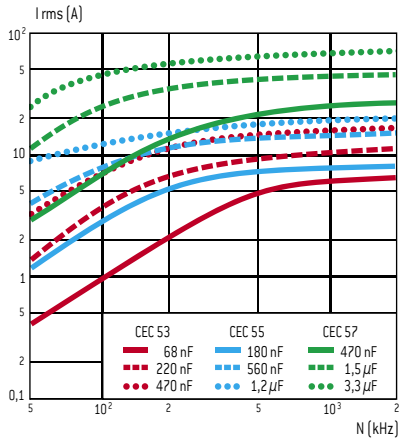




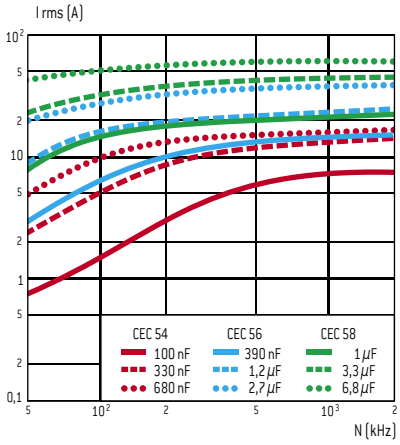
U_{RC} = 25 V $_{DC}$ (Typical curves for Δθ = 20°C).

TYPICAL CURVES: CEC5X Series

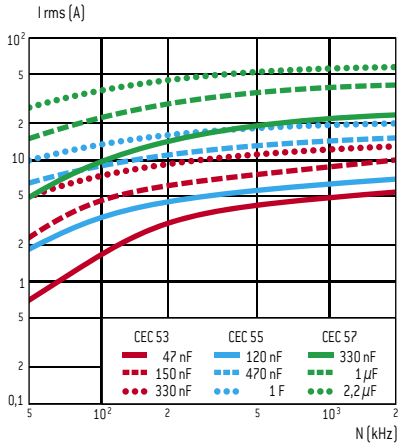
NPO: CURRENT VS FREQUENCY



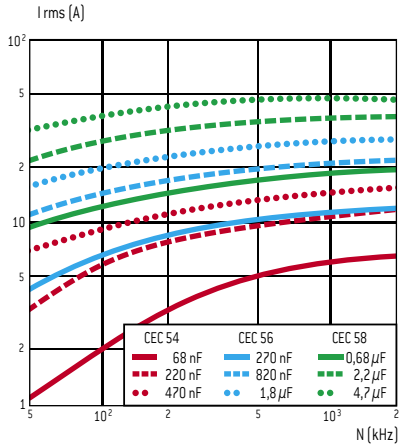
U_{RC} = 63 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



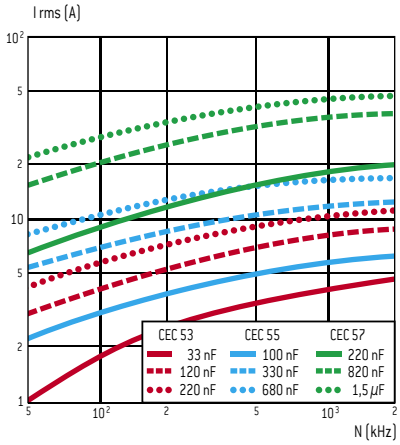
U_{RC} = 63 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



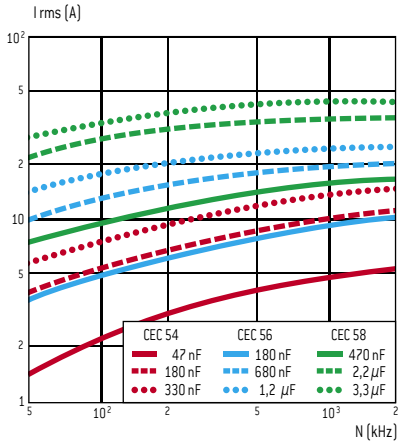
U_{RC} = 100 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



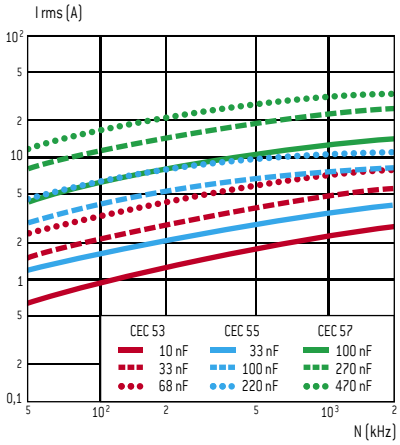
U_{RC} = 100 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



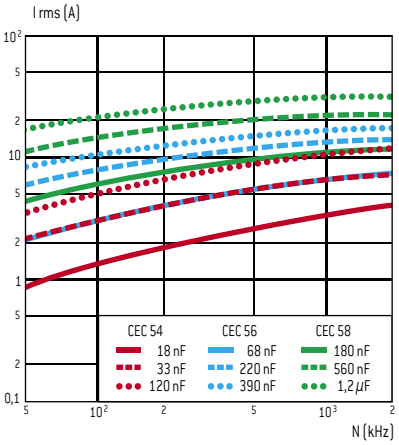
U_{RC} = 200 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



U_{RC} = 200 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).



U_{RC} = 500 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).

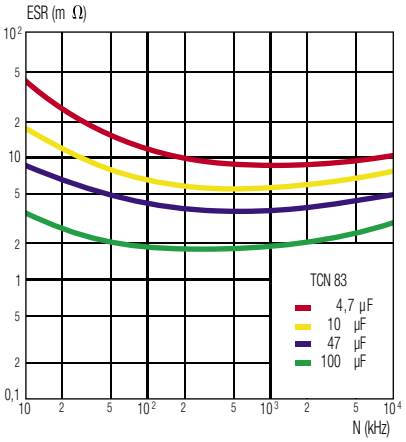


U_{RC} = 500 V_{DC} (Typical curve for $\Delta\theta$ = 20°C).

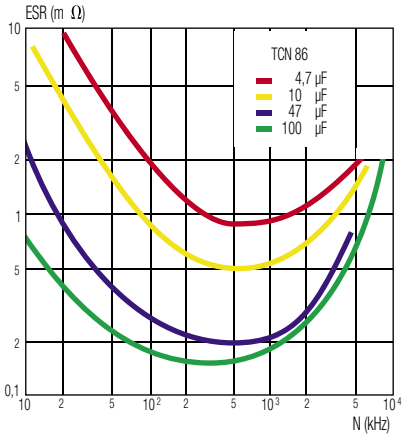
General Information

TYPICAL CURVES: TCN8X Series

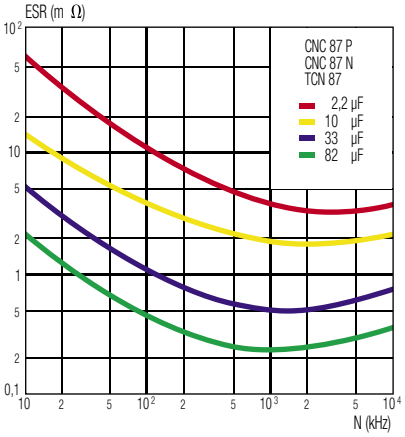
TCN83: TYPICAL EQUIVALENT SERIAL RESISTANCE (ESR) VS FREQUENCY (N)



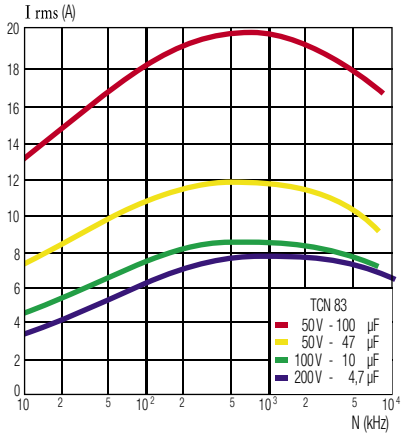
TCN86: TYPICAL EQUIVALENT SERIAL RESISTANCE (ESR) VS FREQUENCY (N)



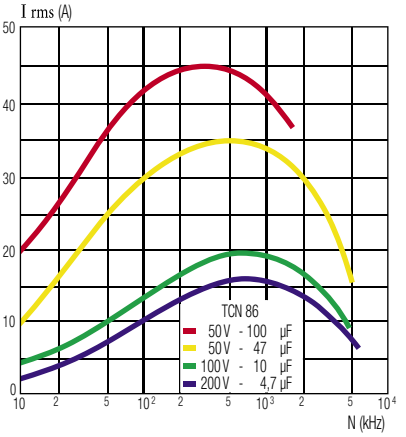
TCN87: TYPICAL EQUIVALENT SERIAL RESISTANCE (ESR) VS FREQUENCY (N)



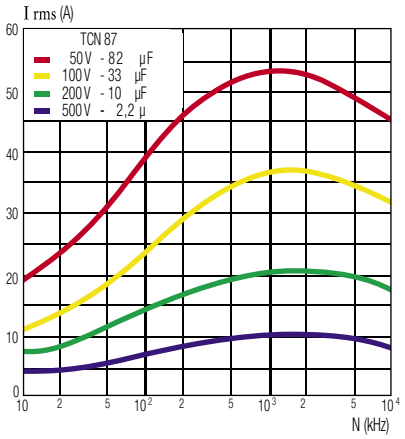
TCN83: CURRENT (I_{RMS}) VS FREQUENCY (N) TYPICAL CURVES FOR $\Delta\theta \leq 20°C$



TCN86: CURRENT (I_{RMS}) VS FREQUENCY (N) TYPICAL CURVES FOR $\Delta\theta \leq 20°C$

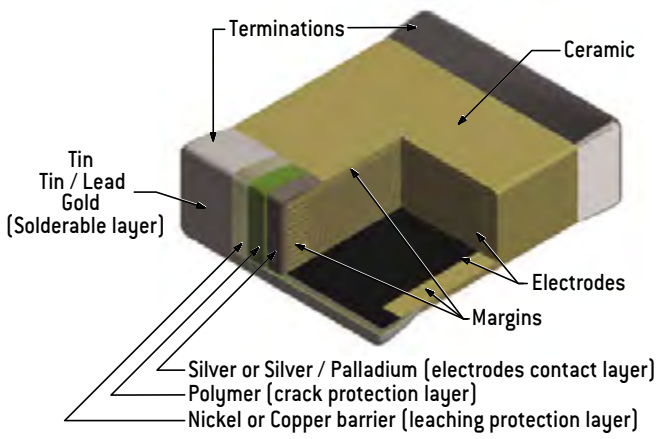


TCN87: CURRENT (I_{RMS}) VS FREQUENCY (N) TYPICAL CURVES FOR $\Delta\theta \leq 20°C$



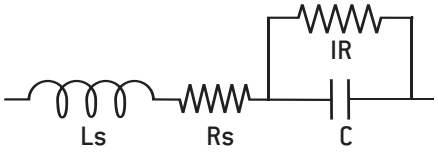
Ceramic Capacitors Technology

MLCC STRUCTURE



EQUIVALENT CIRCUIT

Capacitor is a complex component combining resistive, inductive and capacitive phenomena. A simplified schematic for the equivalent circuit is:



DIELECTRIC CHARACTERISTICS

Insulation Resistance (IR) is the resistance measured under DC voltage across the terminals of the capacitor and consists principally of the parallel resistance shown in the equivalent circuit. As capacitance values and hence the area of dielectric increases, the IR decreases and hence the product (C x IR) is often specified in Ω.F or MΩ.μF.

The Equivalent Series Resistance (ESR) is the sum of the resistive terms which generate heating when capacitor is used under AC voltage at a given frequency (f).

Dissipation factor (DF) is the ration of the apparent power input will turn to heat in the capacitor:

$DF = 2\pi f C ESR$

When a capacitor works under AC voltage, **heat power loss (P),** expressed in Watt, is equal to:

$P = 2\pi f C Vrms^2 DF$

The series inductance (Ls) is due to the currents running through the electrodes. It can distort the operation of the capacitor at high frequency where the **impedance (Z)** is given as:

$Z = Rs + j (Ls.\omega - 1/(C.\omega))$ with $\omega = 2\pi f$

When frequency rises, the capacitive component of capacitors is gradually canceled up to the resonance frequency, where :

$Z = Rs$ and $LsC.\omega^2 = 1$

Above this frequency the capacitor behaves like an inductor.

	P100	NP0	N2200 (C4xx)	BX	2C1	X7R
Dielectric material	Porcelain	Magnesium titanate or Neodynium baryum titanate	Barium zirconate titanate	Baryum titanate ($BaTiO_3$)		
Dielectric constant	15 – 18	20 – 85	450	2,000 – 5,000		
Electrode technology	PME (Precious Metal Electrodes): Ag/Pd					
Capacitance variation between –55°C and +125/°C without DC voltage	(100±30)ppm/°C	(0±30)ppm/°C	(–2,200±500) ppm/°C	±15%	±20%	±15%
Capacitance variation between –55°C and +125/°C with DC rated voltage			0 -15%	15% –25%	20% –30%	Not applicable
Piezo-electric effect	None		None	Yes		
Dielectric absorption	None		Few %	Few %		
Thermal shock sensitive	+		+	++		

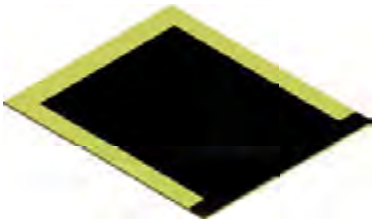
Ceramic Capacitors Technology

MANUFACTURING STEPS

SLIP CASTING

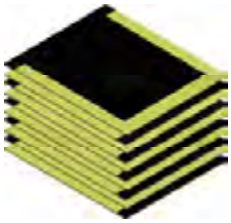
A slurry, a mix of ceramic powder, binder and solvents, is poured onto conveyor belt inside a drying oven, resulting in a dry ceramic sheet.

ELECTRODE SCREEN PRINTING



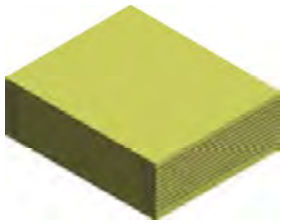
The electrode ink, made from a metal powder mixed with solvents, is printed onto the ceramic sheets using a screen printing process.

STACKING



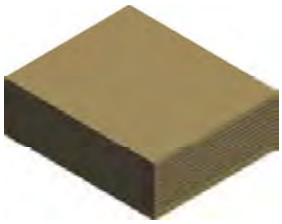
The sheets with electrode printed are stacked to create a multilayer structure.

PRESSING



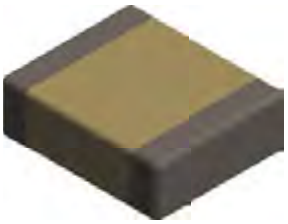
Pressure is applied to the stack to fuse all the separate layers, this created a monolithic structure.

SINTERING



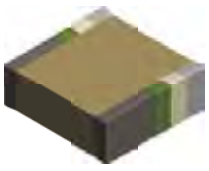
The parts are sintered in an oven with a precise temperature profile which is very important to the characteristics of the capacitors.

TERMINATIONS



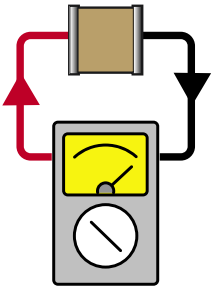
Each terminal of the capacitor is dipped in the termination ink, mix of metal powder, solvents and glass frit and the parts are fired in an oven.

TERMINATIONS PLATING



Stacking + leads soldering + encapsulation
(see pages 10-11)

FINAL TESTING



PACKAGING

User Guide

SMD TERMINATIONS

NON RoHS COMPLIANT	Code	RoHS COMPLIANT	Code	Magnetic	Recommended mounting process						Storage (months)*
					Epoxy bonding	Iron soldering	Wave soldering	Vapor phase soldering	Infrared soldering	Wire bonding	
Ag	**Q**	Ag	**QW / P**	No	●	●	●	●			18
Ag/Pd/Pt	**-**	Ag/Pd/Pt	**W / A**	No	●	●	●				24
Ag/Pd/Pt + dipped Sn/Pb 60/40	**H**	Ag/Pd/Pt + dipped Sn	**HW**	No		●					24
Ag + Ni + electrolytic Sn/Pb 95/5	**C**	Ag + Ni + electrolytic Sn	**CW / S**	Yes		●	●	●	●		18
Ag + Ni + electrolytic Sn/Pb 60/40	**D**	-	**-**	Yes		●	●	●	●		18
-	**-**	Ag + Cu + electrolytic Sn	**C****	No		●	●	●	●		18
Ag + Ni + dipped Sn/Pb 60/40	**E**	-	**-**	Yes		●	●				24
Ag + Ni + Au	**G**	Ag + Ni + Au	**GW**	Yes	●	●	●	●	●	●	36
Ag + Polymer + Ni + Sn/Pb 95/5	**YC**	Ag + Polymer + Ni + Sn	**YCW**	Yes		●	●	●	●		18
Ag + Polymer + Ni + Sn/Pb 60/40	**YD**	-	**-**	Yes		●	●	●	●		18
Ag + Polymer + Ni + Au	**YG**	Ag + Polymer + Ni + Au	**YGW**	Yes	●	●	●	●	●	●	36

Nickel (Ni) or Copper (Cu) barriers amplify thermal shock and are not recommended for chip sizes larger than 3030.

* Storage must be in a dry environment at a temperature of 20°C with a relative humidity below 50%, or preferably in a package enclosing a desiccant.

** Non magnetic chips series only.

SMD ENVIRONMENTAL TESTS

Ceramic chip capacitors for SMD are designed to meet test requirements of **CECC 32100** and **NF C 93133** standards as specified below in compliance with **NF C 20700** and **IEC 68** standards:

- Solderability: **NF C 20758,** 260°C, bath 62/36/2.
- Adherence: 5N force.
- Vibration fatigue test: **NF C 20706,** 20 g, 10 Hz to 2,000 Hz, 12 cycles of 20 minutes each.
- Rapid temperature change: **NF C 20714,** –55°C to + 125°C, 5 cycles.
- Combined climatic test: **IEC 68-2-38.**
- Damp heat: **NF C 20703,** 93 %, H.R., 40°C.
- Endurance test: 1,000 hours, 1.5 U_{RC}, 125°C.

STORAGE OF CHIP CAPACITORS

TINNED OR NON TINNED CHIP CAPACITORS

Storage must be in a dry environment at a temperature of 20°C with a relative humidity below 50 %, or preferably in a packaging enclosing a desiccant.

STORAGE IN INDUSTRIAL ENVIRONMENT:

- 2 years for tin dipped chip capacitors,
- 18 months for tin electroplated chip capacitors,
- 2 years for non tinned chip capacitors,
- 3 years for gold plated chip capacitors.

STORAGE IN CONTROLLED NEUTRAL NITROGEN ENVIRONMENT:

- 4 years for tin dipped or electroplated chip capacitors,
- 4 years for non tinned chip capacitors,
- 5 years for gold plated chip capacitors.

Storage duration should be considered from delivery date and not from batch manufacture date. The tests carried out at final acceptance stage (solderability, susceptibility to solder heat) enable to assess the compatibility to surface mounting of the chips.

User Guide

LEAD STYLES

SURFACE MOUNTING

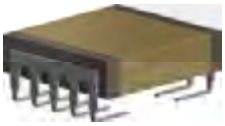
DIL LEADS

P style

PL style

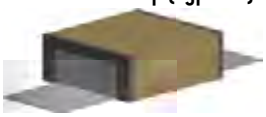
L style

J style

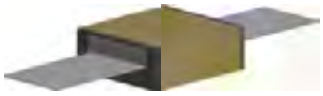


RIBBON LEADS

Micro-strip (type 1)
Short Micro-strip (type 1S)



Axial (Type 2)

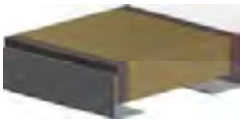


Radial (Type 3)

R style

RX style

RJ style



Please contact Exxelia sales for any lead configuration not shown.

TROUGH-HOLE MOUNTING

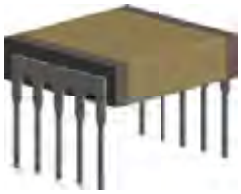
AXIAL AND RADIAL

Radial leads (Type 6)

Radial leads (4 leads)

Axial leads (Type 7)

DIL leads: N style



ENCAPSULATION STYLES

Ceramic encapsulation
(selfprotected)

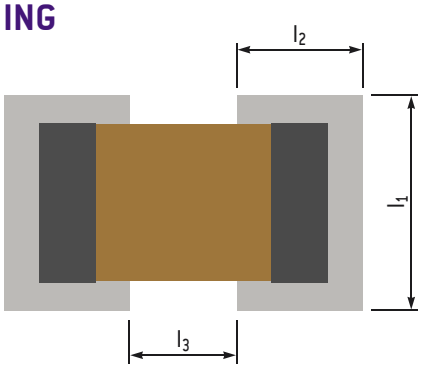
Varnish

Conformal coating

Molding

User Guide

SOLDERING ADVICES FOR REFLOW SOLDERING



Large chips above size 2225 are not recommended to be mounted on epoxy board due to thermal expansion coefficient mismatch between ceramic capacitor and epoxy. Where larger sizes are required, it is recommended to use components with ribbon or other adapted leads so as to absorb thermo-mechanical strains.

Dimensions in inches (in mm)	Reflow soldering						Wave soldering					
	I_1		I_2		I_3		I_1		I_2		I_3	
0402	0.043	(1.1)	0.035	(0.9)	0.012	(0.3)	0.043	(1.1)	0.047	(1.2)	0.012	(0.3)
0403	0.055	(1.4)	0.035	(0.9)	0.012	(0.3)	0.055	(1.4)	0.047	(1.2)	0.012	(0.3)
0504	0.063	(1.6)	0.051	(1.3)	0.016	(0.4)	0.063	(1.6)	0.063	(1.6)	0.016	(0.4)
0603	0.055	(1.4)	0.059	(1.5)	0.02	(0.5)	0.055	(1.4)	0.071	(1.8)	0.02	(0.5)
0805	0.073	(1.85)	0.065	(1.65)	0.024	(0.6)	0.073	(1.85)	0.077	(1.95)	0.024	(0.6)
0907	0.094	(2.4)	0.065	(1.65)	0.035	(0.9)	0.094	(2.4)	0.077	(1.95)	0.035	(0.9)
1005	0.073	(1.85)	0.067	(1.7)	0.039	(1)	0.073	(1.85)	0.079	(2)	0.039	(1)
1206	0.083	(2.1)	0.067	(1.7)	0.059	(1.5)	0.083	(2.1)	0.079	(2)	0.059	(1.5)
1210	0.118	(3)	0.069	(1.75)	0.059	(1.5)	0.118	(3)	0.081	(2.05)	0.059	(1.5)
1605	0.073	(1.85)	0.071	(1.8)	0.087	(2.2)	0.073	(1.85)	0.083	(2.1)	0.087	(2.2)
1806	0.087	(2.2)	0.073	(1.85)	0.102	(2.6)	0.087	(2.2)	0.085	(2.15)	0.102	(2.6)
1812	0.152	(3.85)	0.073	(1.85)	0.102	(2.6)	0.152	(3.85)	0.085	(2.15)	0.102	(2.6)
1825	0.281	(7.15)	0.073	(1.85)	0.102	(2.6)	0.281	(7.15)	0.085	(2.15)	0.102	(2.6)
2210	0.13	(3.3)	0.079	(2)	0.146	(3.7)	0.13	(3.3)	0.091	(2.3)	0.146	(3.7)
2220	0.228	(5.8)	0.079	(2)	0.146	(3.7)	0.228	(5.8)	0.091	(2.3)	0.146	(3.7)
2225	0.281	(7.15)	0.079	(2)	0.146	(3.7)	0.281	(7.15)	0.091	(2.3)	0.146	(3.7)

RECOMMENDED FOOTPRINT FOR SMD CAPACITORS

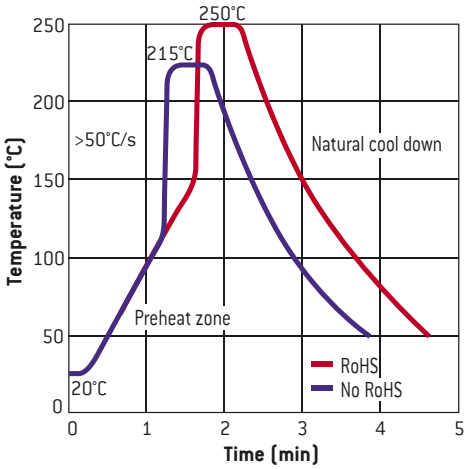
Ceramic is by nature a material which is sensitive both thermally and mechanically. Stresses caused by the physical and thermal properties of the capacitors, substrates and solders are attenuated by the leads.

Wave soldering is unsuitable for sizes larger than 2220 and for the higher ends of capacitance ranges due to possible thermal shock (capacitance values given upon request).

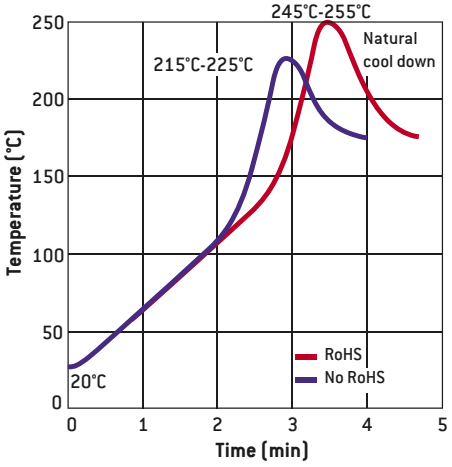
Infrared and vapor phase reflow, are preferred for high reliability applications as inherent thermo-mechanical strains are lower than those inherent to wave soldering.

Whatever the soldering process is, it is highly recommended to apply a thermal cycle, see hereafter our recommended soldering profile:

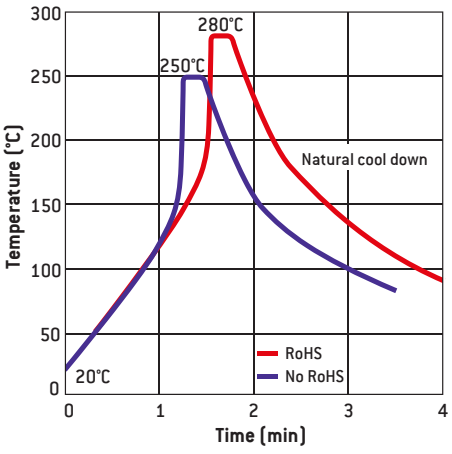
RECOMMENDED VAPOR PHASE REFLOW PROFILE



RECOMMENDED IR REFLOW PROFIL



RECOMMENDED WAVE SOLDERING PROFILE



SOLDERING ADVICES FOR IRON SOLDERING

Attachment with a soldering iron is discouraged due to ceramic brittleness and the process control limitations. In the event that a soldering iron must be used, the following precautions should be observed:

- Use a substrate with chip footprints big enough to allow putting side by side one end of the capacitor and the iron tip without any contact between this tip and the component,
- place the capacitor on this footprint,
- heat the substrate until the capacitor's temperature reaches 150°C minimum (preheating step, maximum 1°C per second),
- place the hot iron tip (a flat tip is preferred) on the footprint **without touching the capacitor.** Use a regulated iron with a 30 watts maximum power. The recommended temperature of the iron is 270 ±10°C. The temperature gap between the capacitor and the iron tip must not exceed 120°C,

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- leave the tip on the footprint for a few seconds in order to increase locally the footprint's temperature,
- use a cored wire solder and put it down on the iron tip. In a preferred way use Sn/Pb/Ag 62/36/2 alloy,
- wait until the solder fillet is formed on the capacitor's termination,
- take away iron and wire solder,
- wait a few minutes so that the substrate and capacitor come back down to the preheating temperature,
- solder the second termination using the same procedure as the first,
- let the soldered component cool down slowly to avoid any thermal shock.

PACKAGING

TAPE AND REEL

The films used on the reels correspond to standard IEC 60286-3. Films are delivered on reels in compliance with document IEC 286-3 dated 1991.

Minimum quantity is 250 chips.

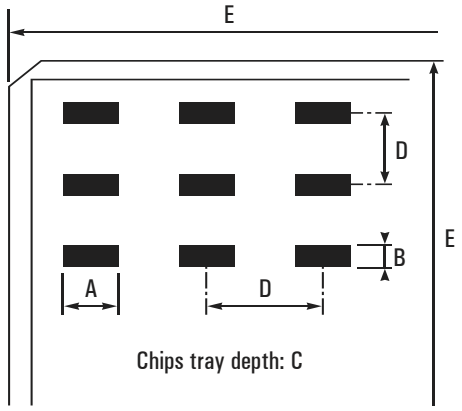
Maximum quantities per reel are as follows:

- Super 8 reel - Ø 180: 2,500 chips.
- Super 8 reel - Ø 330: 10,000 chips.
- Super 12 reel - Ø 180: 1,000 chips.

Reel marking complies with CECC 32100 standard:

- Model.
- Rated capacitance.
- Capacitance tolerance.
- Rated voltage.
- Batch number.

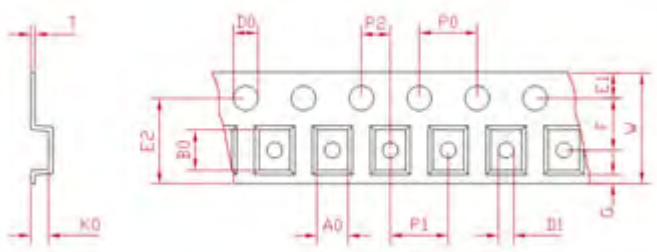
TRAY PACKAGES



DIMENSIONAL CHARACTERISTICS OF CHIPS TRAY PACKAGES

Sizes	Nr. of chips/ package	Oriented chips	Dimensions in inches (in mm)				
			A	B	C	D	E
0402	100	No	Ø 0.112 (Ø 3.02)		0.065 (1.65)	0.167 (4.24)	2 (50.8)
0403	100	No	Ø 0.112 (Ø 3.02)		0.065 (1.65)	0.167 (4.24)	2 (50.8)
0504	100	Yes	0.059 (1.5)	0.045 (1.14)	0.035 (0.89)	0.167 (4.24)	2 (50.8)
0603	340	Yes	0.1 (2.54)	0.06 (1.52)	0.045 (1.14)	0.167 (4.24)	2 (50.8)
0805	100	Yes	0.1 (2.54)	0.06 (1.52)	0.045 (1.14)	0.167 (4.24)	2 (50.8)
1206	100	No	0.14 (3.56)	0.14 (3.56)	0.06 (1.52)	0.167 (4.24)	2 (50.8)
1210	100	Yes	0.14 (3.56)	0.14 (3.56)	0.06 (1.52)	0.167 (4.24)	2 (50.8)
1812	100	No	0.25 (6.35)	0.25 (6.35)	0.13 (3.3)	0.345 (8.76)	4 (101.6)
	25	Yes	0.24 (6.1)	0.265 (6.73)	0.07 (1.78)	0.345 (8.76)	2 (50.8)
2220	100	Yes	0.25 (6.35)	0.25 (6.35)	0.13 (3.3)	0.345 (8.76)	4 (101.6)
	25	Yes	0.24 (6.1)	0.265 (6.73)	0.07 (1.78)	0.345 (8.76)	2(50.8)

HIGH Q CAPACITORS TAPE AND REEL PACKAGING SPECIFICATIONS



Sizes	Type (1)	W±0.3 inches (mm)	F ±0.05 inches (mm)	P1 ±0.1 inches (mm)	T max. inches (mm)	Reel Size inches (mm)	Quantity per Reel
A (0505)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	3'000
A (0505)	V	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	3'000
S (0603)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,016 (0,4)	7,087 (180)	4'000
F (0805)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,016 (0,4)	7,087 (180)	4'000
B (1111)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,012 (0,3)	7,087 (180)	1'000
B (1111)	V	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	1'000
X (2225)	H	0,472 (12)	0,138 (5.5)	0,472 (12)	0,018 (0,45)	12,992 (330)	500
E (4040)	H	0,945 (24)	0,453±0,004 (11.5±0.1)	0,630 (16)	0,018 (0,45)	12,992 (330)	700
E (4040)	V	1,260 (32)	0,559±0,004 (14.2 ±0.1)	0,945 (24)	0,022 (0,55)	15 (381)	350

(1): Horizontal (H) or Vertical (V) orientation in cavities.

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EIA STANDARD CAPACITANCE VALUES

Following EIA standard, the values and multiples that are indicated in the chart below can be ordered. E48, E96 series and intermediary values are available upon request.

E6 (± 20%)	E12 (± 10%)	E24 (± 5%)
10	10	10
		11
	12	12
		13
15	15	15
		16
	18	18
		20
22	22	22
		24
	27	27
		30
33	33	33
		36
	39	39
		43
47	47	47
		51
	56	56
		62
68	68	68
		75
	82	82
		91

EIA CAPACITANCE CODE

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits are significant figures of the capacitance value and the third digit identifies the multiplier.

For capacitance value < 10pF, R designates a decimal point.
See examples below:

EIA code	Capacitance value		
	in pF	in nF	in µF
2R2	2.2	0.0022	0.0000022
6R8	6.8	0.0068	0.0000068
220	22	0.022	0.000022
470	47	0.047	0.000047
181	180	0.18	0.00018
221	220	0.22	0.00022
102	1,000	1	0.001
272	2,700	2.7	0.0027
123	12,000	12	0.012
683	68,000	68	0.068
124	120,000	120	0.12
564	560,000	560	0.56
335	3,300,000	3,300	3.3
825	8,200,000	8,200	8.2
156	15,000,000	15,000	15
686	68,000,000	68,000	68
107	100,000,000	100,000	100
227	220,000,000	220,000	220

PART MARKING VOLTAGE CODES

Use the following voltage code chart for part markings:

Voltage (V)	Code	Letter code
25	250	A
40	400	B
50	500	C
63	630	D
100	101	E
200	201	G
250	251	H
400	401	K
500	501	L
1,000	102	M
2,000	202	P
3,000	302	R
4,000	402	S
5,000	502	T
7,500	752	U
10,000	103	W

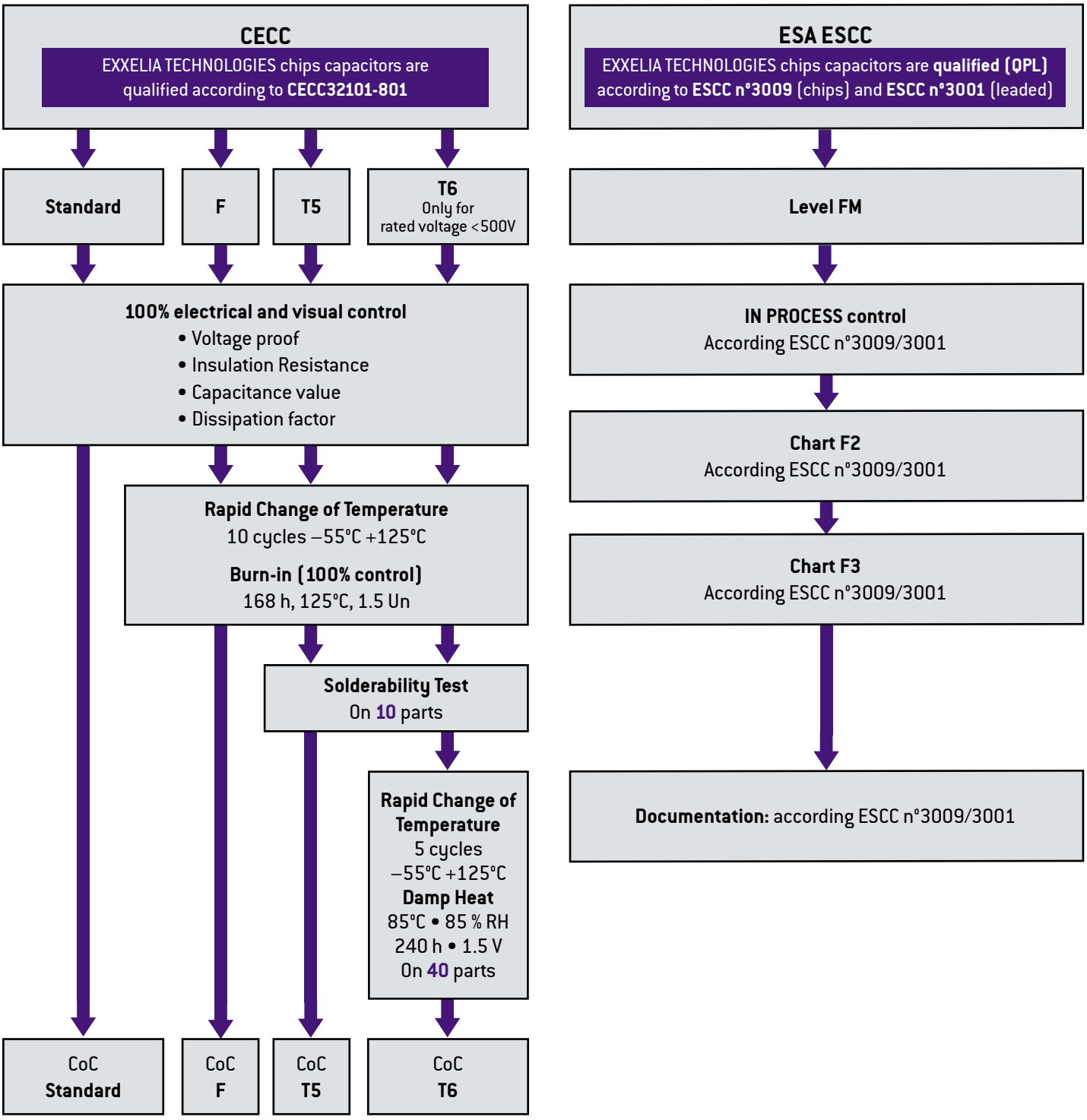
PART MARKING TOLERANCE CODES

Use the following tolerance code chart for part markings:

Tolerance	Letter code
±0.25pF	CU
±0.5pF	DU
±1pF	FU
±1%	F
±2%	G
±5%	J
±10%	K
±20%	M

RELIABILITY LEVELS

Exxelia proposes different reliability levels for the ceramic capacitors for both NP0 and X7R ceramics.



As the world's leading manufacturer of specific passive components, we stand apart through our ability to quickly evaluate the application specific engineering challenges and provide a cost-effective and efficient solutions.

For requirements that cannot be met by catalog products, we offer leading edge solutions in custom configuration: custom geometries, packaging, characteristics, all is possible thanks to our extensive experience and robust development process, while maintaining the highest level of reliability.

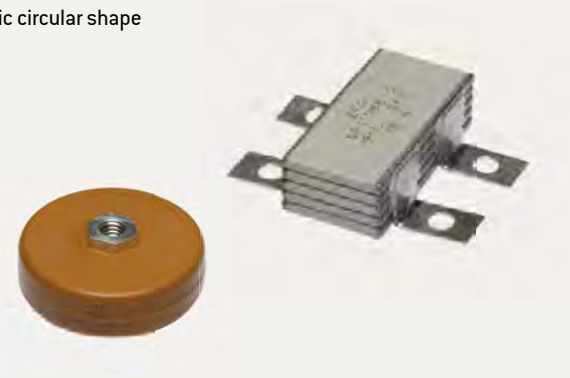
Where necessary, special testing is done to verify requirements, such as low dielectric absorption, ultra-high insulation resistance, low dissipation factor, stability under temperature cycling or under specified environmental conditions, etc.

HIGH CAPACITANCE

- High energy density
- Specific case sizes
- Specific shape of connections (high resistance to vibrations)

HIGH VOLTAGE

- Up to 50 kV
- Specific circular shape

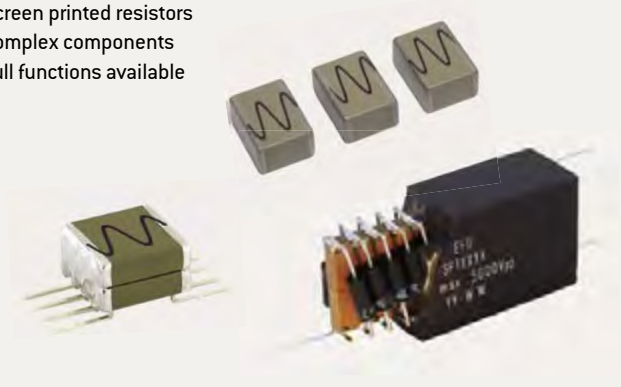


HIGH TEMPERATURE

- Up to 250°C
- Specific shape of connections
- 2,000 hours life time
- HMP soldering

OTHERS

- Screen printed resistors
- Complex components
- Full functions available



General Information

MATERIALS EXPERT

For 50 years and as a market leader, EXXELIA's comprehensive knowledge of the materials properties and performances have enabled us to design capacitors in Porcelain, NP0, BX, 2C1, BP, X7R and –2200ppm/°C ceramics.

CUSTOM DESIGNS

Our catalog products don't meet your application?

Based on the valuable experience accumulated over the design of 2,000+ specific ceramic capacitors, you can trust EXXELIA to define a qualitative custom solution in a time effective manner.

NO OBSOLESCENCE

Choosing a standard or custom EXXELIA product means you won't have to worry about obsolescence.

TYPICAL APPLICATIONS

- Aerospace & Defense: cockpit panels, flight control, radio systems, missile guidance systems…
- Space: military and commercial satellites, launcher…
- Medical: MRI, external defibrillators, implantable devices…
- Telecommunications: base stations…
- Oil and gas: drilling tools, MWD, LWD, wellheads…

ISO 9001 AND AS9100C

Quality is at the core of Exxelia's corporate culture. Each sites has its own certifications.

CERTIFICATIONS

Capacitors manufactured by EXXELIA comply with American and European standards and meet the requirements of many international standards.
For Space qualified parts (ESA QPL), please refer to our catalog «Ceramic capacitors for Space applications».

QUALITY & RELIABILITY

EXXELIA is committed to design and manufacture high quality and reliability products. The test cycles reproducing the most adverse operating conditions over extended periods (up to 10 000 hours) have logged to date well over 5.10^9 hours/°Component.
Failure rate data can be provided upon request.

CONFLICT MINERALS

EXXELIA is committed to an approach based on «Conflict Minerals Compliance». This US SEC rule demands complete traceability and a control mechanism for the mineral procurement chain, encouraging importers to buy only «certified» ore.
We have discontinued relations with suppliers that procure from the Democratic Republic of the Congo or an adjoining country.

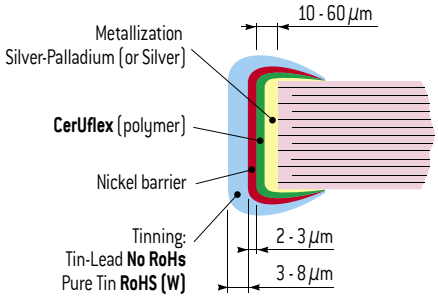
ENVIRONMENT

EXXELIA is committed to applying a robust environmental policy, from product design through to shipment. To control its environmental footprint and reconcile this with the company' functional imperatives, our environmental policy provides for the reduction or elimination of hazardous substances. We also focus on compliance with European Union directives and regulations, notably REACH and RoHS.

RoHS COMPLIANCY

SMD CAPACITORS

The capacitor terminations are generally protected by a nickel barrier formed by electrolytic deposit. This barrier gives chip capacitors leaching performance far exceeding the requirements of all applicable standards. The nickel barrier guarantees a minimum resistance to soldering heat for a period of 1 minute at 260°C in a tin-lead (60/40) or tin-lead-silver (62/36/2) bath without noticeable alteration to the solderability. It also allows repeated soldering-unsoldering and the longer soldering times required by reflow techniques.
However nickel barrier amplifies thermal shock and is not recommended for chip sizes equal or greater than CNC Y (30 30) - (C 282 to C 288 - CNC 80 to CNC 94).



LEADED COMPONENTS

As well as for SMD products, leaded capacitors ranges can also be RoHS. These products, which are characterized by the suffix «W» added to the commercial type, are naturally compatible with the soldering alloys used in RoHS mounting technology. The connections coating is generally an alloy SnAg (with a maximum of 4% Ag). However, on a few products that EXXELIA will precise on request, the coating is pure silver.